



Material Composition Declaration

EPC2252

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/24/2023
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	2.9 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	2.5952	89.1293	93.1156	891293
	Silicon oxide	7631-86-9	0.0174	0.5962		5962
	Silicon nitride	12033-89-5	0.0057	0.1954		1954
	Gallium nitride	25617-97-4	0.0129	0.4431		4431
	Aluminum	7429-90-5	0.0247	0.8491		8491
	Aluminum nitride	24304-00-5	0.0027	0.0941		941
	Titanium	7440-32-6	0.0005	0.0176		176
	Titanium nitride	25583-20-4	0.0235	0.8068		8068
	Copper	7440-50-8	0.0004	0.0142		142
	Tungsten	7440-33-7	0.0029	0.0988		988
	Polyimide		0.0254	0.8709	8709	
Under Bump Metal	Titanium	7440-32-6	0.0004	0.0137	0.0680	137
	Copper	7440-50-8	0.0016	0.0544		544
Solder Bump	Copper	7440-50-8	0.0198	0.6797	6.8164	6797
	Nickel	7440-02-0	0.0118	0.4054		4054
	Tin	7440-31-5	0.1639	5.6281		56281
	Silver	7440-22-4	0.0030	0.1032		1032
Sum in total:			2.9117	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.